

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1	10/574844.app.	US-PGPUB; USPAT; JPO; DERWENT	ADJ	OFF	2008/01/07 09:33
S2	0	("2007/0125412").URPN.	USPAT	ADJ	OFF	2008/01/07 09:34
S3	0	("2007/0125412").URPN.	USPAT	ADJ	OFF	2008/01/07 09:34
S4	0	("2007/0125412").URPN.	USPAT	ADJ	OFF	2008/01/07 09:34
S5	0	PCT/JP04/14680	USPAT	ADJ	OFF	2008/01/07 09:36
S6	1	PCT/JP04/14680	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	OFF	2008/01/07 09:36
S7	10	electrical\$3 ADJ conductive ADJ paste AND thermoelectric\$3	US-PGPUB; USPAT; JPO; DERWENT	ADJ	OFF	2008/01/07 10:09
S8	11	electrical\$3 ADJ conductive ADJ paste AND thermoelectric\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	OFF	2008/01/07 10:09
S9	22	complex NEAR oxide AND paste AND thermoelectric \$3	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	OFF	2008/01/07 10:13
S10	6	"6376763"	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	OFF	2008/01/07 10:17
S11	0	electrical\$3 NEAR conductive NEAR paste NEAR thermoelectric\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	OFF	2008/01/07 10:18
S12	11	electrical\$3 NEAR conductive NEAR paste AND thermoelectric\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	OFF	2008/01/07 10:19
S13	0	("2007/0125412").URPN.	USPAT	ADJ	OFF	2008/01/07 10:19
S14	5	("5168095").PN. OR ("6376763").URPN.	US-PGPUB; USPAT; USOCR	ADJ	OFF	2008/01/07 10:19
S15	174	electrical\$3 AND conduct \$4 NEAR paste AND thermoelectric\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	OFF	2008/01/07 10:24
S16	712	electrical\$3 AND conduct \$4 AND paste AND thermoelectric\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	OFF	2008/01/07 10:24

S17	0	thermoelectric NEAR paste AND oxide NEAR power	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	OFF	2008/01/07 10:40
S18	2	thermoelectric NEAR paste AND oxide NEAR powder	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	OFF	2008/01/07 10:40
S19	6	paste NEAR oxide NEAR powder	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	OFF	2008/01/07 10:40
S20	22	thermoelectric\$5 AND complex NEAR oxide AND paste	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	OFF	2008/01/07 10:41
S21	524	thermoelectric\$5 AND oxide AND paste	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	OFF	2008/01/07 10:44
S22	11	thermoelectric\$5 AND oxide NEAR paste	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	OFF	2008/01/07 10:45
S23	24	thermoelectric\$5 AND powder NEAR paste	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	OFF	2008/01/07 10:45
S24	2881	electrical\$3 ADJ conductive ADJ paste	US-PGPUB; USPAT; JPO; DERWENT	ADJ	OFF	2008/01/07 10:53
S25	71	electrical\$3 ADJ conductive ADJ (paste OR adhesive OR glue) AND thermoelectric\$4	US-PGPUB; USPAT; JPO; DERWENT	ADJ	OFF	2008/01/07 10:55
S26	1864	complex oxide AND (Ca OR Calcium) AND (Co OR Cobalt)	US-PGPUB; USPAT; JPO; DERWENT	ADJ	OFF	2008/01/07 11:14
S27	61	complex oxide AND (Ca OR Calcium) AND (Co OR Cobalt) AND thermoelectric \$3	US-PGPUB; USPAT; JPO; DERWENT	ADJ	OFF	2008/01/07 11:14
S28	1	thermoelectric\$3 AND (powder AND metal) NEAR (paste or epoxy or glue or adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/01/07 11:24
S29	1003	thermoelectric\$3 AND (powder AND metal) AND (paste or epoxy or glue or adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/01/07 11:24
S30	0	thermoelectric\$3 NEAR (powder AND metal) AND (paste or epoxy or glue or adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/01/07 11:24

S31	4	"6376763".pn. OR "5352299".pn.	US-PGPUB; USPAT; JPO; DERWENT	ADJ	OFF	2008/01/08 07:56
S32	223	(complex ADJ oxide) and conducti\$6 AND (paste or glue or adhesive) AND semiconductor	US-PGPUB; USPAT; JPO; DERWENT	ADJ	OFF	2008/01/10 11:20
S33	362	(complex ADJ oxide) and conducti\$6 AND (paste or glue or adhesive) AND semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/01/10 11:20
S34	0	(complex ADJ oxide) NEAR (conducti\$6 AND (paste or glue or adhesive)) AND semiconductor AND thermoelectric	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/01/10 11:43
S35	22	(complex ADJ oxide) AND (conducti\$6 AND (paste or glue or adhesive)) AND semiconductor AND thermoelectric	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/01/10 11:43
S36	22	(complex ADJ oxide) AND (conducti\$6 AND (paste or glue or epoxy OR adhesive)) AND semiconductor AND thermoelectric	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/01/10 15:25
S37	421	(complex ADJ oxide) AND (conducti\$6 AND (paste or glue or epoxy OR adhesive)) AND semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/01/10 15:27
S38	0	(complex ADJ oxide) NEAR (conducti\$6 AND (paste or glue or epoxy OR adhesive)) AND (("n- type" or "n type") AND ("p-type" OR "p type") NEAR semiconductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/01/10 15:28
S39	0	(complex ADJ oxide) NEAR (conducti\$6 AND (paste or glue or epoxy OR adhesive)) AND (("n- type" or "n type") AND ("p-type" OR "p type") NEAR semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/01/10 15:36

S40	22	(complex ADJ oxide) AND (conducti\$6 AND (paste or glue or epoxy OR adhesive)) AND ("n-type" OR "n type") AND ("p-type" OR "p type") NEAR semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/01/10 15:37
S41	2951	(conducti\$6 AND (paste or glue or epoxy OR adhesive)) AND ("n-type" OR "n type") AND ("p-type" OR "p type") NEAR semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/01/10 15:38
S42	8104	(conducti\$6 AND (paste or glue or epoxy OR adhesive)) AND ("n-type" OR "n type") AND ("p-type" OR "p type") AND oxide AND metal AND (semiconductor or "semi conductor")	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/01/10 15:48
S43	3687	(conducti\$6 SAME (paste or glue or epoxy OR adhesive)) AND ("n-type" OR "n type") AND ("p-type" OR "p type") AND oxide AND metal AND (semiconductor or "semi conductor")	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/01/10 15:49
S44	1139	(conducti\$6 SAME (paste or glue or epoxy OR adhesive)) AND ("n-type" OR "n type") AND ("p-type" OR "p type") NEAR (semiconductor or "semi conductor") AND oxide AND metal	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/01/10 15:50
S45	0	(conducti\$6 SAME (paste or glue or epoxy OR adhesive)) AND ("n-type" OR "n type") AND ("p-type" OR "p type") NEAR (semiconductor or "semi conductor") AND oxide AND metal AND 252/518. ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/01/10 15:50

S46	0	(conducti\$6 SAME (paste or glue or epoxy OR adhesive)) AND ("n-type" or "n type") AND ("p-type" OR "p type") NEAR (semiconductor or "semi conductor") AND oxide AND metal AND "252". ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/01/10 15:50
S47	14	(conducti\$6 SAME (paste or glue or epoxy OR adhesive)) AND ("n-type" or "n type") AND ("p-type" OR "p type") NEAR (semiconductor or "semi conductor") AND oxide AND metal AND "252". clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/01/10 15:50
S48	0	252/581.1.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/01/10 15:56
S49	112	252/581.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/01/10 15:56
S50	7	252/581.ccls. and metal and oxide	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/01/10 15:57
S51	992	ceramic AND (metal ADJ powder) AND conductive ADJ paste	US-PGPUB; USPAT; JPO; DERWENT	ADJ	OFF	2008/01/14 08:28
S52	91	powder ADJ ceramic AND (metal ADJ powder) AND conductive ADJ paste	US-PGPUB; USPAT; JPO; DERWENT	ADJ	OFF	2008/01/14 08:30
S53	91	(powder ADJ ceramic) AND (metal ADJ powder) AND conductive ADJ paste	US-PGPUB; USPAT; JPO; DERWENT	ADJ	OFF	2008/01/14 08:30
S54	33	(powder ADJ ceramic) AND (metal ADJ (particles OR powder)) AND (conductive ADJ paste) AND (semiconductor or "semi-conductor")	US-PGPUB; USPAT; JPO; DERWENT	ADJ	OFF	2008/01/14 08:40
S55	36	(powder ADJ ceramic) AND (metal ADJ (particles OR powder)) AND (conductive ADJ (paste OR epoxy OR glue OR adhesive)) AND (semiconductor or "semi-conductor")	US-PGPUB; USPAT; JPO; DERWENT	ADJ	OFF	2008/01/14 08:59

S56	36	(powder ADJ ceramic) AND (metal ADJ (particles OR powder)) AND (conductive ADJ (paste OR epoxy OR glue OR adhesive)) AND ((semiconductor or "semi- conductor") OR thermoelectric\$4)	US-PGPUB; USPAT; JPO; DERWENT	ADJ	OFF	2008/01/14 08:59
S57	36	(powder ADJ ceramic) AND (metal ADJ (particles OR powder)) AND (conductive ADJ (paste OR epoxy OR glue OR adhesive)) AND ((semiconductor or "semi- conductor") OR thermoelectric\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	OFF	2008/01/14 09:00
S58	101	(powder ADJ ceramic) AND (metal ADJ (particles OR powder)) AND (conductive ADJ (paste OR epoxy OR glue OR adhesive))	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	OFF	2008/01/14 09:00
S59	146	(powder ADJ (ceramic OR oxide)) AND (metal ADJ (particles OR powder)) AND (conductive ADJ (paste OR epoxy OR glue OR adhesive))	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	OFF	2008/01/14 09:03
S60	2273	((ceramic OR (complex ADJ oxide))) AND (metal ADJ (particles OR powder)) AND (conductive ADJ (paste OR epoxy OR glue OR adhesive))	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	OFF	2008/01/14 09:43
S61	0	((ceramic OR (complex ADJ oxide))) AND (metal) AND (conductive ADJ (paste OR epoxy OR glue OR adhesive)) "252".clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	OFF	2008/01/14 09:44
S62	427	((ceramic OR (complex ADJ oxide))) AND (metal) AND (conductive ADJ (paste OR epoxy OR glue OR adhesive)) "252".clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT	AND	OFF	2008/01/14 09:44
S63	2	"5422190".pn.	US-PGPUB; USPAT; JPO; DERWENT	ADJ	OFF	2008/01/15 13:55
S64	2	"4859250".pn.	US-PGPUB; USPAT; JPO; DERWENT	ADJ	OFF	2008/01/16 08:06

S65	0	252/518.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	AND	OFF	2008/01/16 12:47
S66	576	252/518.1.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	AND	OFF	2008/01/16 12:47

1/16/2008 12:48:08 PM

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